Halogen -free

Highly heat resistant Halogen-free Multi-layer circuit board materials
高耐熱ハロゲンフリー多層基板材料

Halogen-free

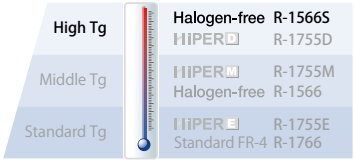
Laminate **R-1566S**
Prepreg **R-1551S**

Applications 用途

Automotive ECU, Automotive module, HEV/EV power control unit, DC/DC converter board, Etc.
車載 ECU、車載モジュール、HEV/EV パワーコントロールユニット、DC/DC コンバータ用基板など

Automotive
オートモーティブ

Added highly heat resistant and tracking resistance to automotive quality R-1566 to improve the reliability of ECU boards used under severe conditions.
従来の R-1566 より高耐熱性と耐トラッキング性を向上し、高温環境下で使用される ECU 用基板の信頼性に貢献



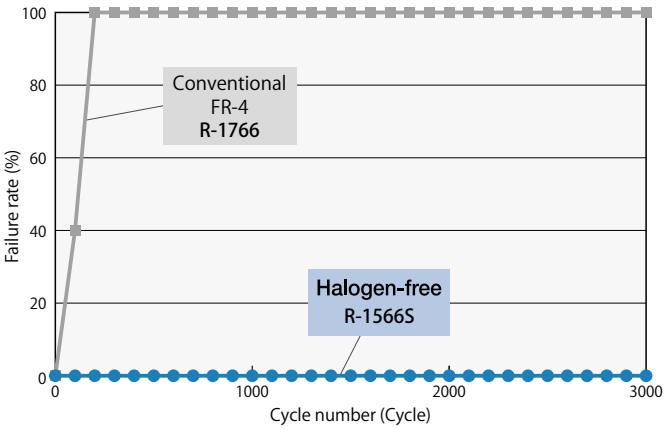
Tg (DSC) 175℃

Td (TGA) 355℃

CTI≧600V*

*actual value

Through-hole reliability スルーホール導通信頼性

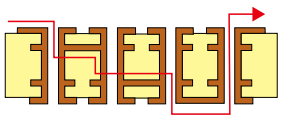


● Condition

Cycle condition	-40℃ (15min)	⇔	160℃ (15min)

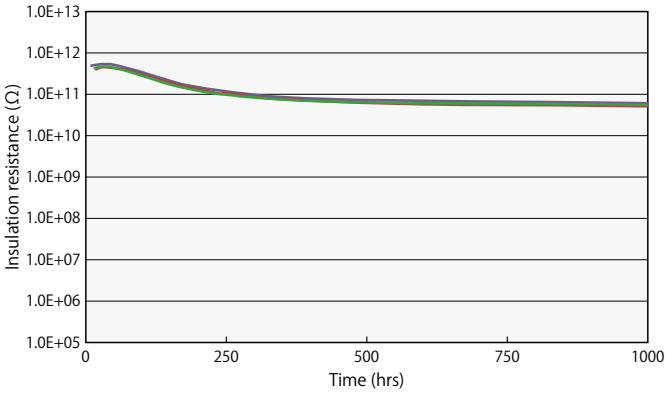
* Failure is over 10% changes of resistance
* 260℃ Peak reflow x 3times as pretreatment

● Construction



Insulation reliability 絶縁信頼性

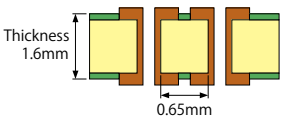
● High voltage CAF evaluation



● Condition

Pretreatment	260℃ Peak reflow x 3times
Condition	85℃ 85%RH DC 350V
Through-hole wall to wall distance	0.65mm

● Construction



General properties 一般特性

Item		Test method	Condition	Unit	Halogen-free R-1566S	Conventional Halogen-free R-1566(W)
Glass transition temp.(Tg)		DSC	A	℃	175	148
		TMA			170	145
Thermal decomposition temp.(Td)		TGA	A	℃	355	350
CTE z-axis	α1	IPC-TM-650 2.4.24	A	ppm/℃	40	40
	α2				180	180
T288(with copper)		IPC-TM-650 2.4.24.1	A	min	10	3
Peel strength	1oz(35μm)	IPC-TM-650 2.4.8	A	kN/m	1.6	1.8

The sample thickness is 0.8mm.

Our Halogen-free materials are based on JPCA-ES-01-2003 standard and others. 当社ハロゲンフリー材料は、JPCA-ES-01-2003 などの定義によるものです。
The above data are typical values and not guaranteed values. 上記データは当社測定による代表値であり、保証値ではありません。

Please see the page for "Notes before you use" 商品のご採用に当たっての注意事項は こちら

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